

**METHOD AND STRUCTURE FOR COOLING A DUAL CHIP MODULE
WITH ONE HIGH POWER CHIP**

ABSTRACT

Disclosed is a cooling structure which has individual spreaders or caps mounted on the chips. The thickness of the high power spreader or cap exceeds the thickness of the lower power spreaders to ensure that the high power spreader achieves the highest plane and mates to a heat sink with the smallest interface gap. The variable and higher gaps between the lower power spreaders and the heat sink base are accommodated by compressible thermal pad or grease materials.